

SOT639-2

plastic thermal enhanced bottom chip carrier; 16 terminals;
body 3 x 3 x 0.65 mm

20 June 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HBCC16
Package type industry code	HBCC16
Package style descriptive code	HBCC (thermal enhanced bottom chip carrier)
Package body material type	P (plastic)
JEDEC package outline code	MO-217
Mounting method type	S (surface mount)
Issue date	12-3-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.9	-	3	3.1	mm
E	package width	2.9	-	3	3.1	mm
A	seated height	-	-	0.8	0.8	mm
A ₂	package height	0.6	-	0.65	0.7	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	16	-	



2. Package outline

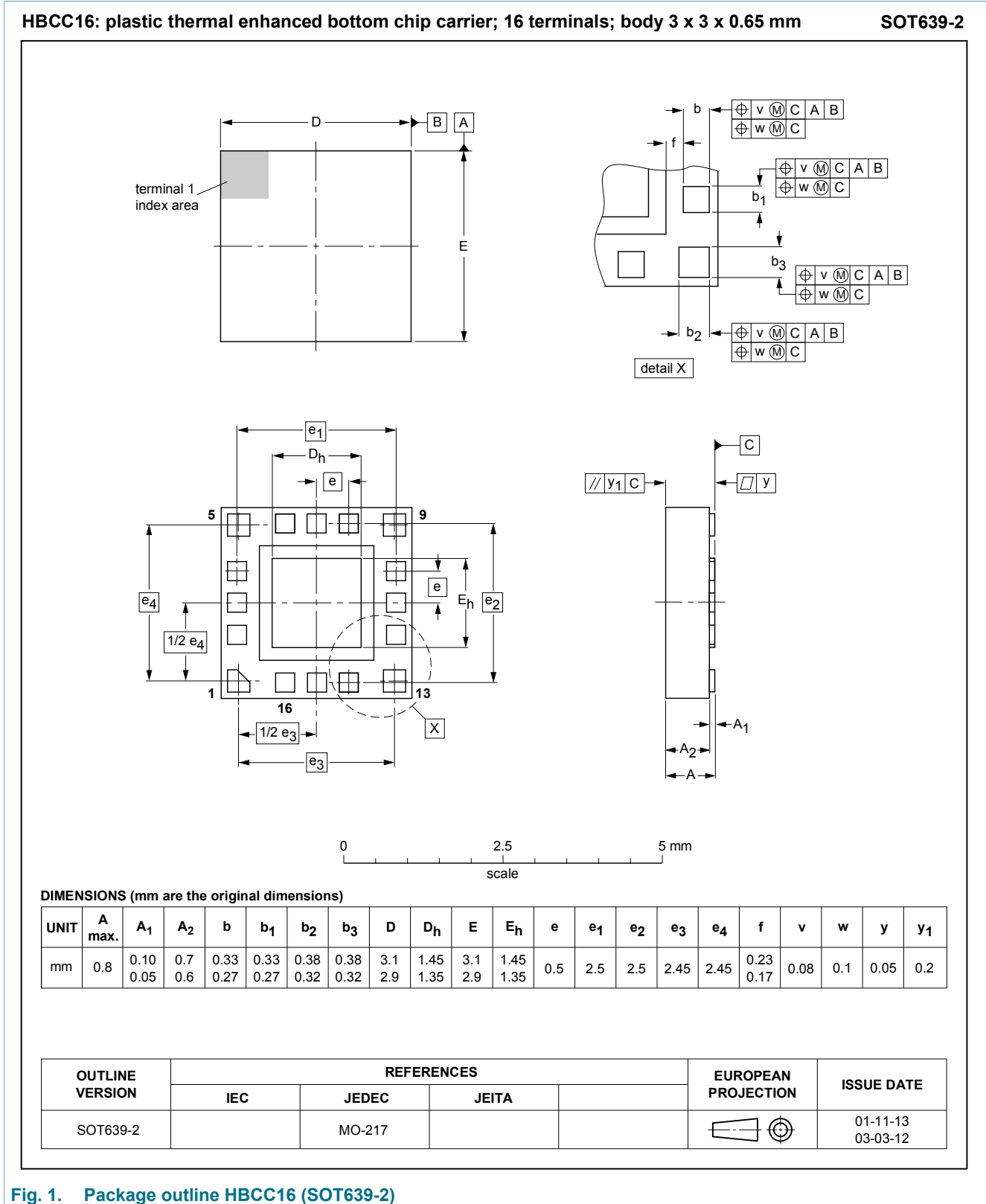


Fig. 1. Package outline HBCC16 (SOT639-2)

3. Soldering

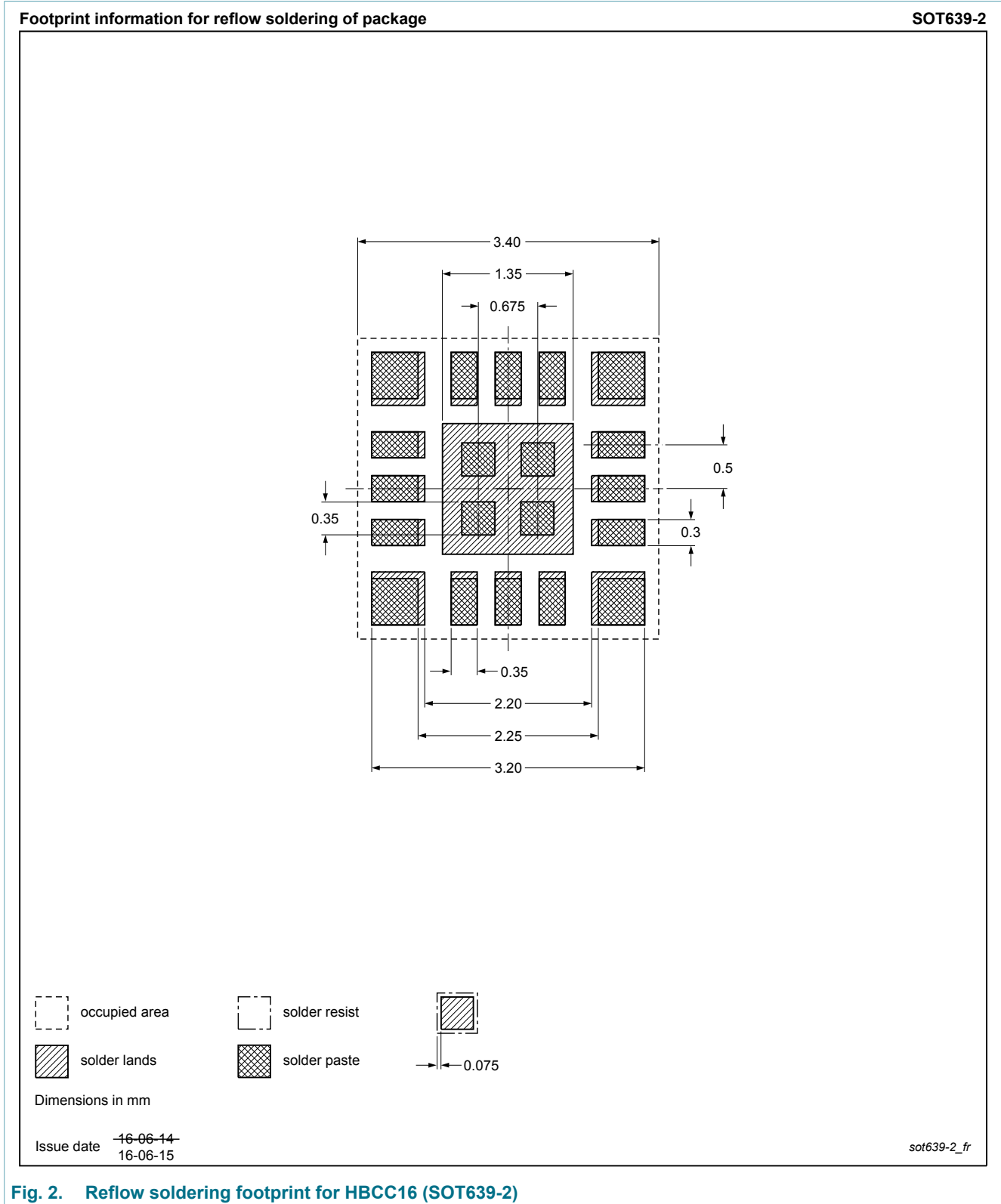


Fig. 2. Reflow soldering footprint for HBCC16 (SOT639-2)

4. Legal information

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Date of release: 20 June 2016
